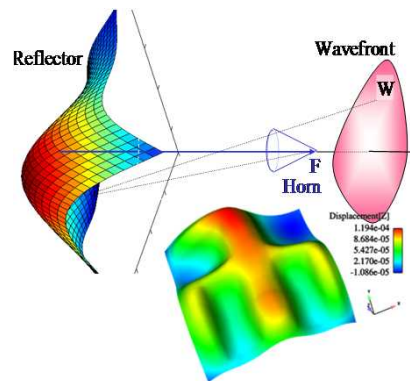


# 1526 – Applied Mechanics Development

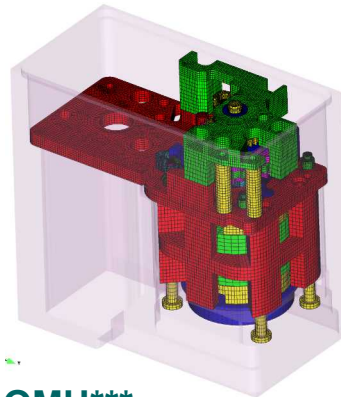
SAND2007-4345P

**Mission: To provide research and development expertise in solid mechanics and structural dynamics to accomplish Sandia's goals in MESA\* vision and SBE\*\* process.**

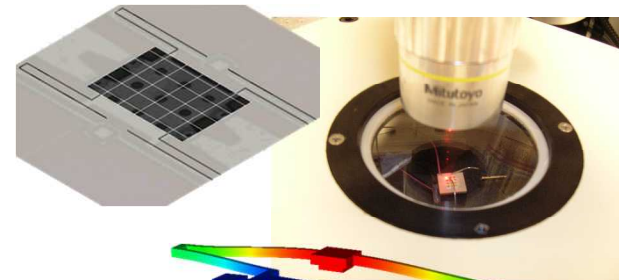
## Adaptive Structures and Smart Materials



## Component Design, Production and Packaging

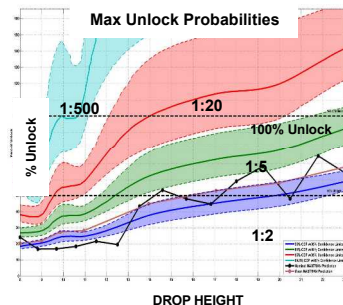


## Microscale Diagnostics and Coupled-physics Response

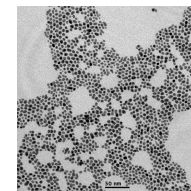
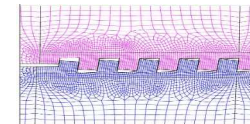


RF MEMS

## Probabilistic Mechanics and QMU\*\*\*



## Mechanics of Interface and Nanosystems



Transmission electron micrograph of approximately 5 nm diameter silver nanoparticles. These filler particles are being used in thermal interface materials for microelectronic cooling.

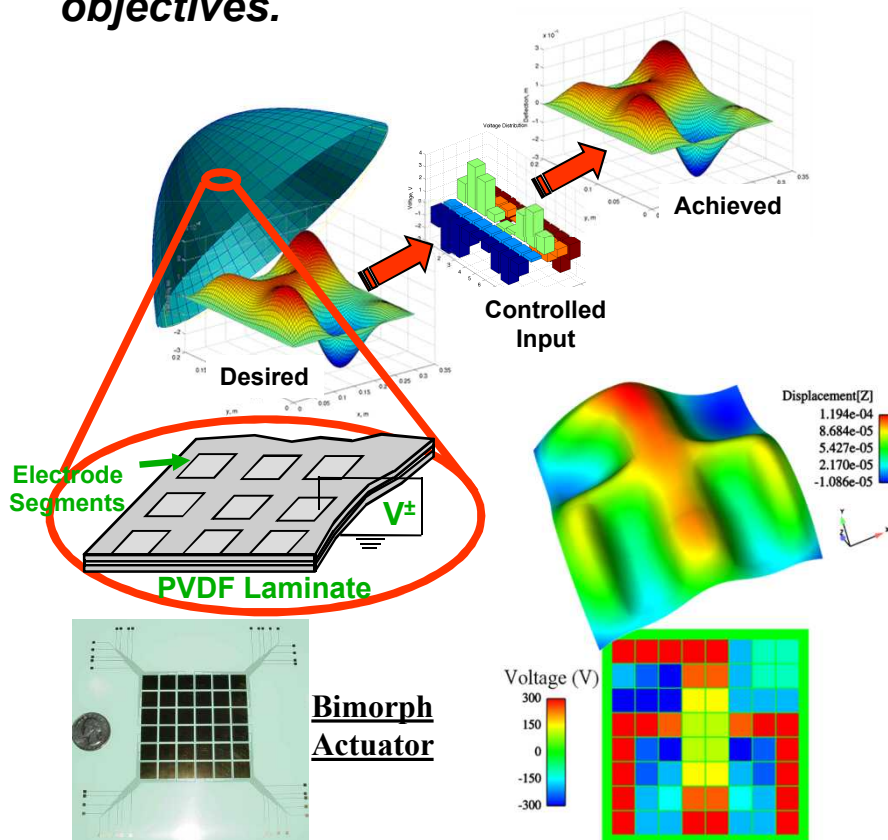
\* MESA: Microsystems and Engineering Science Applications;

\*\* SBE: Science-Based Engineering;

\*\*\* QMU: Quantifying Margins and Uncertainty Analysis

# 1526 – Adaptive Structures and Smart Materials

***To develop smart structures that have ability to sense, analyze, and act according to prescribed performance objectives.***



## Capabilities

- Excellent, in-depth knowledge of behavior, performance, and limitations of smart materials:
  - shape memory alloys;*
  - piezoelectric compounds.*
- Expertise in smart structure design:
  - DOD real-time reconfigurable mirrors.*
- Constitutive models:
  - capturing phase transformation,*
  - polarization reversal, and domain switching.*
- Control algorithm development:
  - shape control of an antenna membrane with distributed piezoelectric patches*

## Customers

- DOD, DOE, DHS

## Contacts

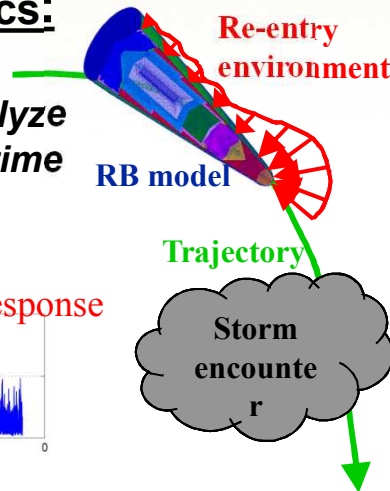
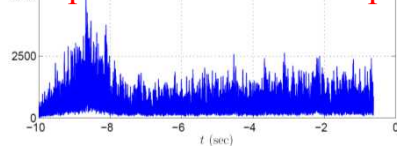
- Pavel Chaplya (pmchapl@sandia.gov)
- Jordan Massad (jemassa@sandia.gov)

# 1526 – Probabilistic Mechanics and Quantifying Margins & Uncertainty

## Probabilistic Mechanics:

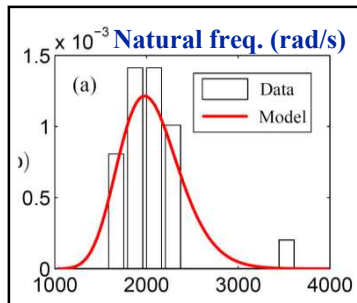
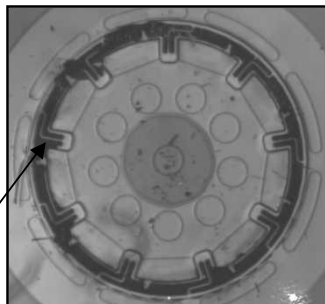
*Applying advanced stochastic models to analyze mechanical response to time and / or spatially random phenomena.*

Component vibration response



## Margin & Uncertainty Analysis:

*Developing and demonstrating methodology to quantifying and assessing margins and uncertainty.*



MEMS Inertia Switch: observe significant unit-to-unit variability

## Capabilities

- Expertise in random vibration, stochastic mechanics, Uncertainty Quantification, and Quantifying Margins & Uncertainty;
- Toolkit for simulation of Gaussian and non-Gaussian random variables, vectors, processes, and fields;
- Procedures to incorporate random samples with deterministic ASC codes;
- Stochastic model calibration and validation;
- Methods for reliability / margin assessment under limited data;
- Solution of stochastic differential equations  
*Stochastic finite elements.*

## Customers

- DOE, DOD, DHS

## Contacts

- Rich Field (rvfield@sandia.gov)

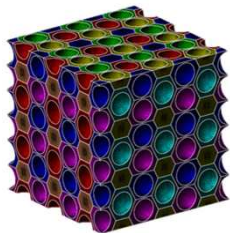


# 1526 – Component Design, Production and Packaging

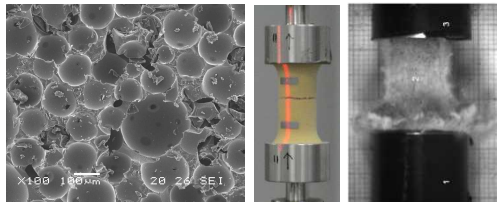
## Foam Constitutive Modeling:

- *Is a focal point of collaborative efforts at Sandia;*
- *Analyze foam behavior at cell level;*
- *Develop models for variety of foams and densities.*

*Foam models*

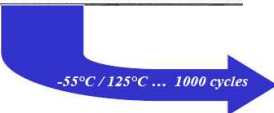
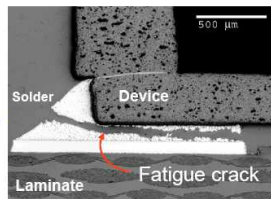
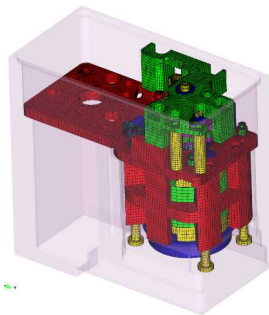
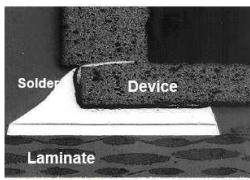


*Foam under tensile stress*



## Soldered Interconnections:

*To investigate and predict lifetime of solder joints.*



*Thermal Mechanical Fatigue*

## Component Responses:

*To assess component responses under shock and vibration.*

## Capabilities

- Failure analysis:
  - Modeling coarsening in solder joints;*
  - Solder Interconnect Predictor (SIP) code;*
  - Cracking in foams and yield surfaces;*
  - Assessing performance of components and quantifying safety margin.*
- Constitutive models:
  - Foam plasticity model;*
  - Visco-plastic foam model;*
  - Effect of coarsening in solder on strength.*

## Customers

- DOE NW, DOD

## Contacts

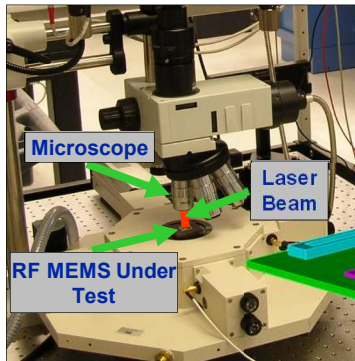
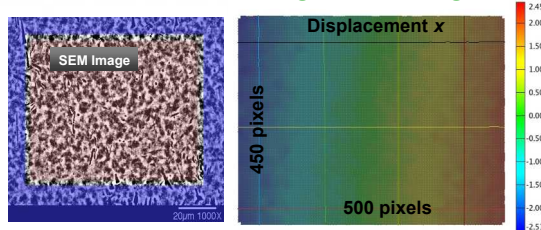
- Foam & joints: Mike Neilsen (mkneils@sandia.gov)
- Components: Clay Fulcher (cwfulch@sandia.gov)

# 1526 – Microscale Diagnostics and Coupled-physics Response

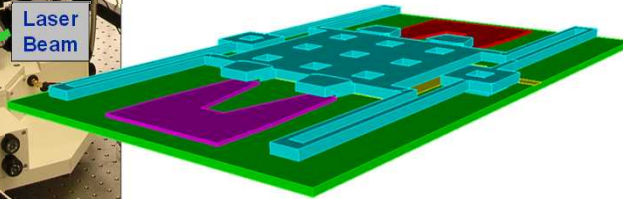
*To understand, predict and diagnose mechanical behavior of microsystems.*



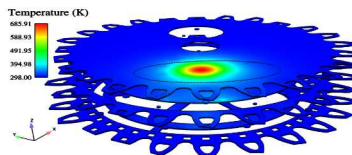
**DIC: Material testing at  $\mu\text{m}$  lengths**



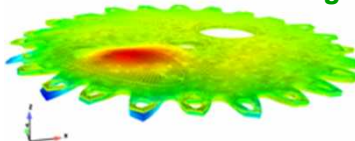
**Laser Doppler Vibrometry to measure contact motion in RF MEMS**



**Laser heating of MEMS**



**Surface deformed due to laser heating**



## Capabilities

- Diagnostic techniques:  
*Digital Image Correlation (DIC);  
Laser Doppler velocimetry (LDV).*
- Coupled-physics analysis (Calagio):  
*Electro-thermal mechanics;  
Opto-thermal mechanics.*
- Micro-scale models:  
*Size-dependent properties;  
Nonlinear dynamic responses;  
Lubrication and gas damping.*

## Customers

- DOE NW, DOD

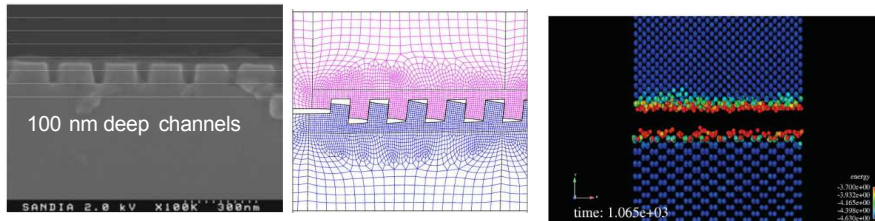
## Contacts

- DIC: Philip Reu (plreu@sandia.gov)
- LDV: Anton Sumali (hsumali@sandia.gov)
- Calagio: Channy Wong (ccwong@sandia.gov)

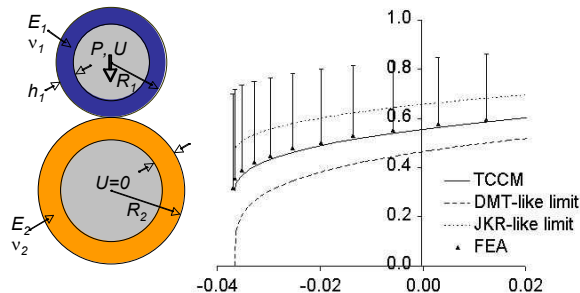
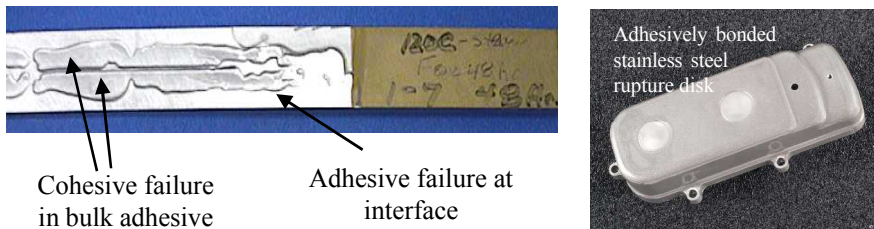
# 1526 – Mechanics of Interface and Nano-systems

***To understand, assess, and model the interaction at material interface and the mechanical behavior of nano-systems.***

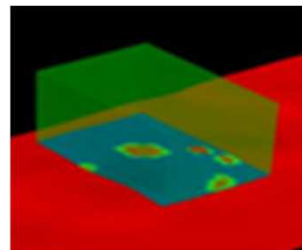
## ***Patterned nanoscale interfacial roughness***



## ***Unique test technique to age a bonded sample***



## ***Contact mechanics theory***



## ***Multi-asperity contact***

## **Capabilities**

- Expertise in interfacial engineering:  
*Patterned interface at nanoscale to enhance the toughness of a thin film;*  
*Applying cohesive zone model to analyze debonding of adhesive materials.*
- Nano-scale models:  
*Thin Coating Contact Mechanics (TCCM) for discrete asperity contact simulations;*  
*Contact algorithm and energy dissipation model for sliding friction.*

## **Customers**

- DOE NW, DOD

## **Contacts**

- Interface: Dave Reedy (edreedy@sandia.gov)
- Friction: Mike Starr (mjstarr@sandia.gov)